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09/475,452	12/30/1999	ANAND MURTHY	042390.P7794	6341

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[REDACTED] ART UNIT [REDACTED] PAPER NUMBER

2815

DATE MAILED: 03/21/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

A7

<b>Office Action Summary</b>	<b>Application No.</b>	<b>Applicant(s)</b>	
	09/475,452	MURTHY ET AL.	
	<b>Examiner</b>	<b>Art Unit</b>	
	Eugene Lee	2815	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

#### Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### Status

1) Responsive to communication(s) filed on 07 January 2003.

2a) This action is FINAL.                  2b) This action is non-final.

3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

#### Disposition of Claims

4) Claim(s) 1-14 is/are pending in the application.

4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.

5) Claim(s) \_\_\_\_\_ is/are allowed.

6) Claim(s) 1-14 is/are rejected.

7) Claim(s) \_\_\_\_\_ is/are objected to.

8) Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### Application Papers

9) The specification is objected to by the Examiner.

10) The drawing(s) filed on 30 December 1999 is/are: a) accepted or b) objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).

11) The proposed drawing correction filed on \_\_\_\_\_ is: a) approved b) disapproved by the Examiner.  
If approved, corrected drawings are required in reply to this Office action.

12) The oath or declaration is objected to by the Examiner.

#### Priority under 35 U.S.C. §§ 119 and 120

13) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).

a) All b) Some \* c) None of:

1. Certified copies of the priority documents have been received.

2. Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.

3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

14) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).  
a) The translation of the foreign language provisional application has been received.

15) Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

#### Attachment(s)

1) <input type="checkbox"/> Notice of References Cited (PTO-892)	4) <input type="checkbox"/> Interview Summary (PTO-413) Paper No(s). _____
2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)	5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)
3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449) Paper No(s) _____	6) <input type="checkbox"/> Other: _____

## DETAILED ACTION

### *Drawings*

1. FIG. 1 should be designated by a legend such as --Prior Art-- because only that which is old is illustrated. See MPEP § 608.02(g). A proposed drawing correction or corrected drawings are required in reply to the Office action to avoid abandonment of the application. The objection to the drawings will not be held in abeyance.

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### *Claim Rejections - 35 USC § 102*

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

The changes made to 35 U.S.C. 102(e) by the American Inventors Protection Act of 1999 (AIPA) do not apply to the examination of this application as the application being examined was not (1) filed on or after November 29, 2000, or (2) voluntarily published under 35 U.S.C. 122(b). Therefore, this application is examined under 35 U.S.C. 102(e) prior to the amendment by the AIPA (pre-AIPA 35 U.S.C. 102(e)).

3. Claims 1, 8, 9, and 12 are rejected under 35 U.S.C. 102(b) as being anticipated by Krivokapic '587. Krivokapic discloses (see, for example, FIG. 2p) a transistor (MOS device) 300 comprising a substrate (first conductivity region) 201, gate oxide (gate dielectric) 208, gate

(gate electrode) 210, spacer (sidewall spacers) 219, source 217 and drain 218. The distance between the source and drain define a channel wherein the distance directly beneath the gate electrode is larger than the distance deeper into the substrate. Regarding claim 12, see, for example, column 9, lines 19-40 and element 241.

***Claim Rejections - 35 USC § 103***

4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

5. Claim 2 is rejected under 35 U.S.C. 103(a) as being unpatentable over Krivokapic '587 as applied to claims 1, 8, 9 and 12 above, and further in view of Takeuchi '351. Krivokapic does not disclose the source/drain regions extending above the gate dielectric and wherein the top surface of said silicon or silicon alloy is spaced further from said gate electrode than the silicon or silicon alloy adjacent to said gate dielectric. However, Takeuchi teaches (see, for example, FIG. 11 (c)) a MOSFET comprising elevated source and drain regions 7B comprising a facet. In column 12, lines 45-63, Takeuchi teaches that such a structure provides reduced parasitic capacitance. Therefore, it would have been obvious to one of ordinary skill in the art at the time of invention to use this structure in Krivokapic's invention in order to reduce parasitic capacitance.

6. Claim 3 is rejected under 35 U.S.C. 103(a) as being unpatentable over Krivokapic '587 as applied to claims 1, 8, 9 and 12 above, and further in view of Choi '582. Krivokapic does not

disclose a gate dielectric layer being thicker beneath the outside edge of said gate electrode than the gate dielectric layer beneath the center of said gate electrode. However, Choi discloses (see, for example, FIG. 2) a semiconductor device comprising a gate insulating film with both sides thicker than a thickness in the center. Choi teaches (see, for example, abstract) that such a gate insulating film reduces hot carrier effects. Therefore, it would have been obvious to one of ordinary skill in the art at the time of invention to use the gate insulating film of Choi in Krivokapic's invention in order to reduce hot carrier effects.

7. Claim 4 is rejected under 35 U.S.C. 103(a) as being unpatentable over Krivokapic '587 in view of Takeuchi '351 as applied to claim 2 above, and further in view of Choi '582. Krivokapic in view of Takeuchi does not disclose a gate dielectric layer being thicker beneath the outside edge of said gate electrode than the gate dielectric layer beneath the center of said gate electrode. However, Choi discloses (see, for example, FIG. 2) a semiconductor device comprising a gate insulating film with both sides thicker than a thickness in the center. Choi teaches (see, for example, abstract) that such a gate insulating film reduces hot carrier effects. Therefore, it would have been obvious to one of ordinary skill in the art at the time of invention to use the gate insulating film of Choi in Krivokapic in view of Takeuchi in order to reduce hot carrier effects.

8. Claims 5 and 6 are rejected under 35 U.S.C. 103(a) as being unpatentable over Krivokapic '587 as applied to claims 1, 8, 9 and 12 above, and further in view of Choi et al. '088. Krivokapic does not disclose a pair of deposited silicon or silicon alloy regions having a first conductivity type formed between said pair of deposited silicon or silicon alloy source/drain regions of said second conductivity type and said first conductivity type region. However, Choi (see, for example, FIG. 2 and FIG. 3) a structure 106 comprising halo regions 120, 122. Choi

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teaches that halo regions provide higher punchthrough voltage. Therefore, it would have been obvious to one of ordinary skill in the art at the time of invention to use halo regions in order to attain a higher punchthrough voltage.

9. Claims 7, 10 and 11 are rejected under 35 U.S.C. 103(a) as being unpatentable over Krivokapic '587. Krivokapic does not disclose an inflection point which occurs between 50-200 A laterally beneath said gate electrode and at a depth of between 25-200 A beneath said gate dielectric. However, it would have been obvious to one of ordinary skill in the art at the time of invention was made to use these depths, since it has been held that where the general conditions of a claim are disclosed in the prior art, discovering the optimum or working ranges involves only routine skill in the art. In re Aller, 105 USPQ 233.

Regarding claims 10 and 11, Krivokapic does not disclose the concentration of said deposited silicon or silicon alloy source/drain regions of a second conductivity type having a concentration between  $1X10^{18} / \text{cm}^3 - 3X10^{21} / \text{cm}^3$  or approximately  $1X10^{21} / \text{cm}^3$ . However, it would have been obvious to one of ordinary skill in the art at the time of invention was made to use these concentrations, since it has been held that where the general conditions of a claim are disclosed in the prior art, discovering the optimum or working ranges involves only routine skill in the art. In re Aller, 105 USPQ 233.

10. Claim 13 is rejected under 35 U.S.C. 103(a) as being unpatentable over Krivokapic '587 as applied to claims 1, 8, 9 and 12 above, and further in view of Pfiester '315 and further in view of Takeuchi '351. Krivokapic does not disclose silicon-germanium alloy source/drain regions. However, Pfiester discloses (see, for example, column 6, lines 15-30 and column 12, lines 35-42) that combining silicon with germanium will improve electrical conductance. Therefore it would

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have been obvious to one of ordinary skill in the art at the time of invention to combine silicon and germanium in the source/drain regions of Krivokapic in order to improve the electrical conductance of the transistor.

Krivokapic in view of Pfiester does not disclose the source/drain regions extending above the gate dielectric and wherein the top surface of said silicon or silicon alloy is spaced further from said gate electrode than the silicon or silicon alloy adjacent to said gate dielectric. However, Takeuchi teaches (see, for example, FIG. 11(c)) a MOSFET comprising elevated source and drain regions 7B comprising a facet. In column 12, lines 45-63, Takeuchi teaches that such a structure provides reduced parasitic capacitance. Therefore, it would have been obvious to one of ordinary skill in the art at the time of invention to use this structure in Krivokapic in view of Pfiester in order to reduce parasitic capacitance.

11. Claim 14 is rejected under 35 U.S.C. 103(a) as being unpatentable over Krivokapic '587 in view of Pfiester '315 in view of Takeuchi '351 as applied to claim 13 above, and further in view of Choi '582. Krivokapic in view of Pfiester in view of Takeuchi does not disclose a gate dielectric layer being thicker beneath the outside edges of said gate electrode than the gate dielectric layer beneath the center of said gate electrode. However, Choi discloses (see, for example, FIG. 2) a semiconductor device comprising a gate insulating film with both sides thicker than a thickness in the center. Choi teaches (see, for example, abstract) that such a gate insulating film reduces hot carrier effects. Therefore it would have been obvious to one of ordinary skill in the art at the time of invention to use the gate insulating film in order to reduce hot carrier effects.

***Response to Arguments***

12. Applicant's arguments filed 1/07/03 have been fully considered but they are not persuasive.

Regarding applicant's arguments that the pair of source/drain regions 217 and 218 do not extend underneath the gate electrode 210 and gate dielectric 208, the Examiner respectfully disagrees. According to Merriam Webster's Dictionary, "beneath" is defined as "in or to a lower position". From FIG. 2p, Krivokapic clearly shows the source/drain regions 217/218 beneath a gate 210 and gate oxide 208. It should also be noted that refractory layer 241 is a part of the gate 210. From FIG. 2o, Krivokapic shows the gate 210 extending substantially over the source and drain region 217 and 218. In that same gate, a salicidation process is performed that forms a salicided metal layer into the gate 210. Therefore, in this manner also, Krivokapic shows the source/drain region 217 and 218 underneath the gate electrode 210 and gate dielectric 208.

Regarding the applicant's argument that one of ordinary skill in the art would not be motivated to utilize Pfiester's silicon germanium source/drain regions in Krivokapic's invention, the Examiner respectfully disagrees. In FIG. 2, Pfiester shows a transistor structure that is clearly in the same art as the applicant's invention and Krivokapic's invention. In column 6, lines 15-30, Pfiester clearly states that the doping of a silicon region with germanium will reduce the number of grain boundaries and therefore improve electrical conductance. Such a process can be extended to Krivokapic's invention wherein Krivokapic discloses silicon regions (source and drain) wherein the number of grain boundaries of source and drain regions may also be reduced and, hence, improve the source and drain regions' electrical conductance.

In response to applicant's argument that the Examiner's conclusion of obviousness is based upon improper hindsight reasoning, it must be recognized that any judgment on obviousness is in any sense necessarily a reconstruction based upon hindsight reasoning. But so long as it takes into account only knowledge which was within the level of ordinary skill at the time of invention was made, and does not include knowledge gleaned only from the Applicant's disclosure, such a reconstruction is proper, In re McLaughlin, 443 F. 2d 1392; 170 USPQ 209 (CCPA 1971).

*Conclusion*

**THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

**INFORMATION ON HOW TO CONTACT THE USPTO**

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Eugene Lee whose telephone number is 703-305-5695. The examiner can normally be reached on M-F 8-5.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Eddie C. Lee can be reached on 703-308-1690. The fax phone numbers for the organization where this application or proceeding is assigned are 703-308-7722 for regular communications and 703-308-7722 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

Eugene Lee  
March 6, 2003



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